MAXIM

Supplier Name: Chipbond Tech. Corp.
Company Address: No. 3, Li Hsin 5 Rd. Science Park, Hsinchu, Taiwan, R.O.C.
Responder Contact: Kenny-Chen
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Responder Title: QS Engineer
Date of Response 2008/10/21

Responder Signature: Kenny Chen

Instructions

Suppliers must provide the identity and % weight of ALL substances of very high concern (SVHC) present in products supplied to Maxim. SVHCs are defined by REACH Article 57 and in accordance with Directive 67/548/EEC. The criteria is set out in REACH Annex XIII. For more information see http://ec.europa.eu/environment/chemicals/reach/reach_intro.htm .

The list of SVHC substances is only for the currently known candidate listing as of Oct 1 2008. Additional updates to this listing are expected and additional requests for data on those new substances as added will be sent.

Data is to supplied for each material type/formulation used in our products. Where multiple suppliers are used, worse case data (highest value) should be shown. Examples: Material Type = Mold Compound, Name/Formula = Sumitomo EME-G600. Material Type = Leadframe, Name/Formula = Cu alloy C194.

Where there is no content of the substance, enter 0%.
Insert additional rows as needed to reflect content of substances per material used

		% Weight of Substance/CAS number															
		Anthracene (CAS No. 120-12-7)	diaminodiphenylmethane (CAS No. 101-77-9)	Dibutyl phthalate (DBP) (CAS No. 84-74-2)	Cyclododecane (CAS No. 294-62-2)	Cobalt dichloride (CAS No. 7545-79-9)	Diarsenic pentaoxide (CAS No. 1303-28-2)	Diarsenic trioxide (CAS No. 1327-53-3)	dichromate, dihydrate (CAS No. 7789-12-0)	butyl-2,4,6-trinitro-m-xylene (musk	ethyl(hexyl)phthalate) (DEHP) (CAS No. 117-81-7)	ocyclododecane (HBCDD) (CAS No. 25637-99-	chain chlorinated paraffins (SCCPs)	Bis(tributyltin)oxide (CAS No. 56-35-9)	Lead hydrogen arsenate (CAS No. 7784-40-9)	Triethyl arsenate (CAS No. 15606-95-8)	butyl phthalate (BBP) (CAS No. 85-68-7)
Material Type	Solder balls																
Material Name	High lead solder balls (Sn5 / Pb95)	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Type	solder balls																
Material Name	Eutectic solder balls (Sn63 / Pb37)	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Type	Under bump metal																
Material Name	Copper metal target	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Type	Under bump metal																
Material Name	Titanium metal target	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Type	Wafer Coating																
Material Name	BCB - CYCLOTENE* 4026 - 46 Advanced Electronics Resin	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%